AMD Xilinx - XC2VP4-6FGG256I Datasheet

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	752
Number of Logic Elements/Cells	6768
Total RAM Bits	516096
Number of I/O	140
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp4-6fgg256i

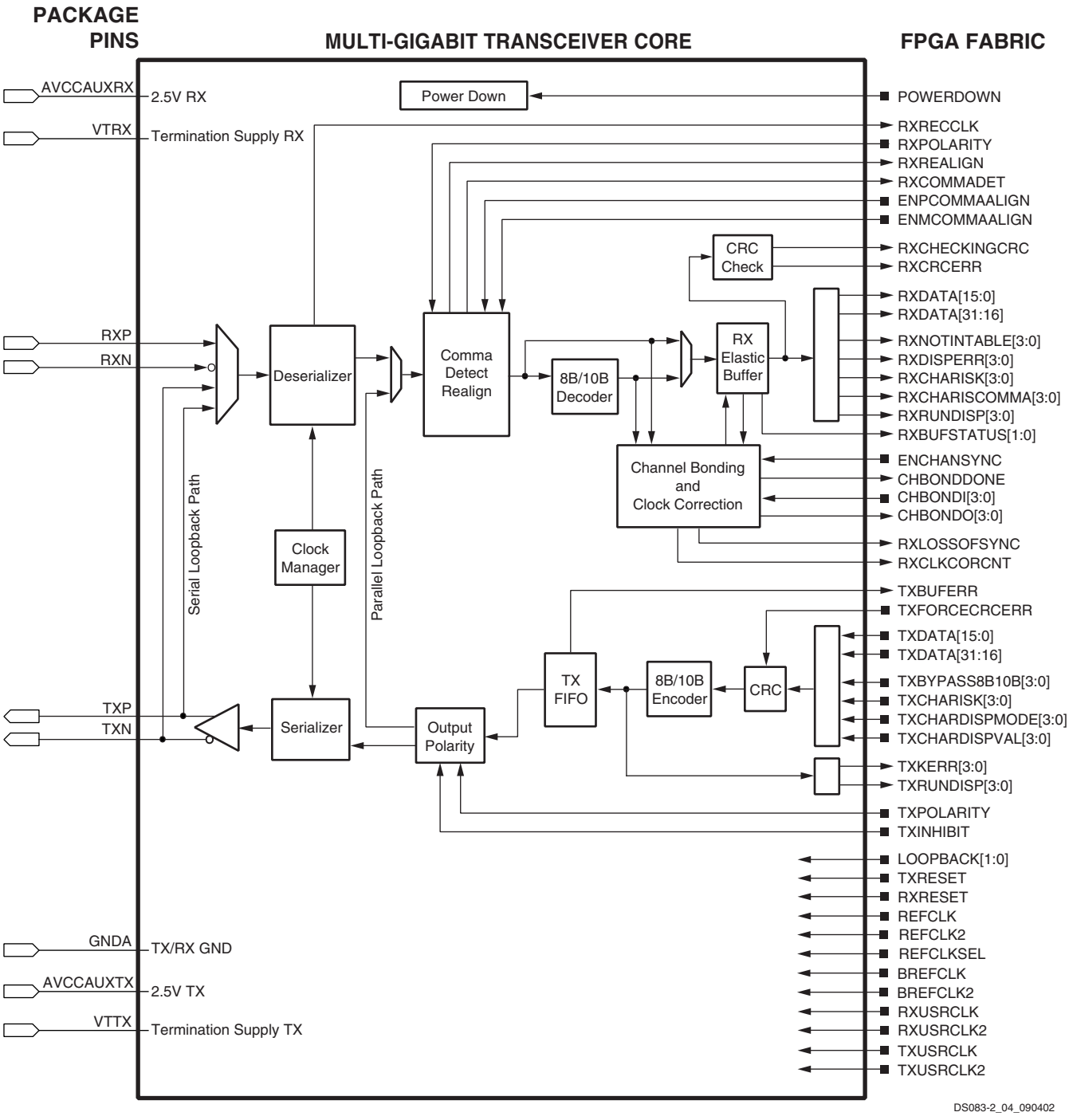

Figure 10: **RocketIO Transceiver Block Diagram**

Output Swing and Pre-emphasis

The output swing and pre-emphasis levels of the RocketIO MGTs are fully programmable. Each is controlled via attributes at configuration, but can be modified via partial reconfiguration.

The programmable output swing control can adjust the differential output level between 400 mV and 800 mV in four increments of 100 mV.

With pre-emphasis, the differential voltage swing is boosted to create a stronger rising waveform. This method compensates for high-frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This pre-emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: **Absolute Maximum Ratings**

Symbol	Description[1]		Virtex-II Pro X	Virtex-II Pro	Units
V_{CCINT}	Internal supply voltage relative to GND		–0.5 to 1.6		V
V_{CCAUX}	Auxiliary supply voltage relative to GND		–0.5 to 3.0		V
V_{CCO}	Output drivers supply voltage relative to GND		–0.5 to 3.75		V
V_{BATT}	Key memory battery backup supply		–0.5 to 4.05		V
V_{REF}	Input reference voltage		–0.3 to 3.75		V
V_{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
V_{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUXTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 3.0	–0.5 to 3.0	V
V_{TRX}	Terminal receive supply voltage relative to GND		–0.5 to 3.0	–0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND		–0.5 to 1.6	–0.5 to 3.0	V
T_{STG}	Storage temperature (ambient)		–65 to +150		°C
T_{SOL}	Maximum soldering temperature[2]	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T_J	Maximum junction temperature[2]		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the **Device Packaging and Thermal Characteristics Guide** information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to **XAPP659** for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT} power supply must ramp on, monotonically, no faster than 200 µs and no slower than 50 ms. Ramp-on is defined as: 0 V_{DC} to minimum supply voltages (see Table 2).

V_{CCAUX} and V_{CCO} can power on at any ramp rate. Power supplies can be turned on in any sequence.

Table 5 shows the minimum current required by Virtex-II Pro devices for proper power-on and configuration.

If the current minimums shown in Table 5 are met, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

For more information on V_{CCAUX}, V_{CCO}, and configuration mode, refer to Chapter 3 in the *Virtex-II Pro Platform FPGA User Guide*.

Table 5: **Power-On Current for Virtex-II Pro Devices**

Symbol	Device											Units
	XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VPX20	XC2VP30	XC2VP40	XC2VP50	XC2VP70	XC2VPX70	XC2VP100	
$I_{CCINTMIN}$	500	500	500	600	600	800	1050	1250	1700	1700	2200	mA
$I_{CCAUXMIN}$	250	250	250	250	250	250	250	250	250	250	250	mA
I_{CCOMIN}	100	100	100	100	100	100	100	100	100	100	100	mA

Notes:
1. Power-on current parameter values are specified for Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.5.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note **XAPP623** for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO}, but only if V_{CCO} does not have excessive noise. Staying within simultaneously switching output (SSO) limits is essential for keeping power supply noise to a minimum. Refer to **XAPP689**, "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place at a rate no faster than 10 mV per millisecond.

Recommended practices that can help reduce jitter and period distortion are described in Xilinx Answer Record 13756.

LVDS DC Specifications (LVDS_25)

Table 8: **LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.602	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.898			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	247	350	454	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100	350	600	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

Extended LVDS DC Specifications (LVDSEXT_25)

Table 9: **Extended LVDS DC Specifications**

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.38	2.5	2.63	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals			1.785	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.715			V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	440		820	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.250	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25V	100		1000	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.3	1.2	2.2	V

LVPECL DC Specifications (LVPECL_25)

These values are valid when driving a 100 Ω differential load only, i.e., a 100 Ω resistor between the two receiver pins. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. Table 10 summarizes the DC output specifications of LVPECL. For more information on using LVPECL, see the *Virtex-II Pro Platform FPGA User Guide*.

Table 10: **LVPECL DC Specifications**

DC Parameter	V_{CCO} = 2.375V		V_{CCO} = 2.5V		V_{CCO} = 2.625V		Units
	Min	Max	Min	Max	Min	Max	
V_{OH}	1.35	1.495	1.475	1.62	1.6	1.745	V
V_{OL}	0.565	0.755	0.69	0.88	0.815	1.005	V
V_{IH}	0.8	2.0	0.8	2.0	0.8	2.0	V
V_{IL}	0.5	1.7	0.5	1.7	0.5	1.7	V
Differential Input Voltage	0.100	1.5	0.100	1.5	0.100	1.5	V

IOB Output Switching Characteristics Standard Adjustments

Table 38 gives all standard-specific adjustments for output delays terminating at pads, based on standard capacitive load, C_{REF}. Output delays terminating at a pad are specified for LVCMOS25 with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown.

Table 38: **IOB Output Switching Characteristics Standard Adjustments**

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
LVTTL (Low-Voltage Transistor-Transistor Logic), Slow, 2 mA	LVTTL_S2	T_{OLVTTL_S2}	5.42	6.24	6.86	ns
LVTTL, Slow, 4 mA	LVTTL_S4	T_{OLVTTL_S4}	3.09	3.55	3.91	ns
LVTTL, Slow, 6 mA	LVTTL_S6	T_{OLVTTL_S6}	2.26	2.60	2.86	ns
LVTTL, Slow, 8 mA	LVTTL_S8	T_{OLVTTL_S8}	1.47	1.69	1.86	ns
LVTTL, Slow, 12 mA	LVTTL_S12	T_{OLVTTL_S12}	1.02	1.18	1.29	ns
LVTTL, Slow, 16 mA	LVTTL_S16	T_{OLVTTL_S16}	0.46	0.53	0.58	ns
LVTTL, Slow, 24 mA	LVTTL_S24	T_{OLVTTL_S24}	0.37	0.42	0.47	ns
LVTTL, Fast, 2 mA	LVTTL_F2	T_{OLVTTL_F2}	4.42	5.09	5.59	ns
LVTTL, Fast, 4 mA	LVTTL_F4	T_{OLVTTL_F4}	1.95	2.24	2.46	ns
LVTTL, Fast, 6 mA	LVTTL_F6	T_{OLVTTL_F6}	1.10	1.26	1.39	ns
LVTTL, Fast, 8 mA	LVTTL_F8	T_{OLVTTL_F8}	0.40	0.46	0.51	ns
LVTTL, Fast, 12 mA	LVTTL_F12	T_{OLVTTL_F12}	0.24	0.27	0.30	ns
LVTTL, Fast, 16 mA	LVTTL_F16	T_{OLVTTL_F16}	0.05	0.06	0.07	ns
LVTTL, Fast, 24 mA	LVTTL_F24	T_{OLVTTL_F24}	–0.01	–0.01	–0.01	ns
LVCMOS (Low-Voltage CMOS), 3.3V, Slow, 2 mA	LVCMOS33_S2	$T_{OLVCMOS33\_S2}$	5.42	6.23	6.86	ns
LVCMOS, 3.3V, Slow, 4 mA	LVCMOS33_S4	$T_{OLVCMOS33\_S4}$	3.14	3.61	3.97	ns
LVCMOS, 3.3V, Slow, 6 mA	LVCMOS33_S6	$T_{OLVCMOS33\_S6}$	2.26	2.60	2.86	ns
LVCMOS, 3.3V, Slow, 8 mA	LVCMOS33_S8	$T_{OLVCMOS33\_S8}$	1.47	1.69	1.86	ns
LVCMOS, 3.3V, Slow, 12 mA	LVCMOS33_S12	$T_{OLVCMOS33\_S12}$	1.03	1.18	1.30	ns
LVCMOS, 3.3V, Slow, 16 mA	LVCMOS33_S16	$T_{OLVCMOS33\_S16}$	0.45	0.52	0.57	ns
LVCMOS, 3.3V, Slow, 24 mA	LVCMOS33_S24	$T_{OLVCMOS33\_S24}$	0.39	0.44	0.49	ns
LVCMOS, 3.3V, Fast, 2 mA	LVCMOS33_F2	$T_{OLVCMOS33\_F2}$	4.46	5.13	5.64	ns
LVCMOS, 3.3V, Fast, 4 mA	LVCMOS33_F4	$T_{OLVCMOS33\_F4}$	1.96	2.25	2.48	ns
LVCMOS, 3.3V, Fast, 6 mA	LVCMOS33_F6	$T_{OLVCMOS33\_F6}$	1.11	1.28	1.40	ns
LVCMOS, 3.3V, Fast, 8 mA	LVCMOS33_F8	$T_{OLVCMOS33\_F8}$	0.41	0.47	0.52	ns
LVCMOS, 3.3V, Fast, 12 mA	LVCMOS33_F12	$T_{OLVCMOS33\_F12}$	0.23	0.26	0.28	ns
LVCMOS, 3.3V, Fast, 16 mA	LVCMOS33_F16	$T_{OLVCMOS33\_F16}$	0.02	0.02	0.03	ns
LVCMOS, 3.3V, Fast, 24 mA	LVCMOS33_F24	$T_{OLVCMOS33\_F24}$	–0.07	–0.08	–0.09	ns
LVCMOS, 2.5V, Slow, 2 mA	LVCMOS25_S2	$T_{OLVCMOS25\_S2}$	4.12	4.74	5.21	ns
LVCMOS, 2.5V, Slow, 4 mA	LVCMOS25_S4	$T_{OLVCMOS25\_S4}$	2.43	2.80	3.07	ns
LVCMOS, 2.5V, Slow, 6 mA	LVCMOS25_S6	$T_{OLVCMOS25\_S6}$	1.76	2.02	2.22	ns
LVCMOS, 2.5V, Slow, 8 mA	LVCMOS25_S8	$T_{OLVCMOS25\_S8}$	1.04	1.19	1.31	ns
LVCMOS, 2.5V, Slow, 12 mA	LVCMOS25_S12	$T_{OLVCMOS25\_S12}$	0.76	0.87	0.96	ns
LVCMOS, 2.5V, Slow, 16 mA	LVCMOS25_S16	$T_{OLVCMOS25\_S16}$	0.41	0.47	0.52	ns
LVCMOS, 2.5V, Slow, 24 mA	LVCMOS25_S24	$T_{OLVCMOS25\_S24}$	0.23	0.26	0.28	ns
LVCMOS, 2.5V, Fast, 2 mA	LVCMOS25_F2	$T_{OLVCMOS25\_F2}$	3.29	3.78	4.16	ns
LVCMOS, 2.5V, Fast, 4 mA	LVCMOS25_F4	$T_{OLVCMOS25\_F4}$	1.31	1.50	1.65	ns

Table 67: **Example Pin-to-Pin Setup/Hold: Source-Synchronous Configuration**

Description	Symbol	Device	Speed Grade			Units
			–7	–6	–5	
Example Data Input Set-Up and Hold Times Relative to a Forwarded Clock Input Pin,(1) Using DCM and Global Clock Buffer. Values represent an 18-bit bus located in Banks 2, 3, 6, or 7 and grouped to one Horizontal Global Clock Line. TRACE must be used to determine the actual values for any given design. For situations where clock and data inputs conform to different standards, adjust the setup and hold values accordingly using the values shown in IOB Input Switching Characteristics Standard Adjustments, page 25.						
No Delay Global Clock and IFF(2) with DCM	T_{PSDCM_0}/T_{PHDCM_0}	XC2VP2	0.23/0.39	0.21/0.42	0.21/0.42	ns
		XC2VP4	0.26/0.37	0.24/0.40	0.24/0.41	ns
		XC2VP7	0.18/ 0.36	0.18/ 0.40	0.18/ 0.41	ns
		XC2VP20	0.14/ 0.41	0.13/ 0.42	0.12/ 0.44	ns
		XC2VPX20	0.14/ 0.41	0.13/ 0.42	0.12/ 0.44	ns
		XC2VP30	0.29/ 0.25	0.31/ 0.24	0.31/ 0.24	ns
		XC2VP40	0.25/ 0.30	0.26/ 0.29	0.27/ 0.29	ns
		XC2VP50	0.18/ 0.36	0.18/ 0.38	0.17/ 0.39	ns
		XC2VP70	0.18/ 0.37	0.18/ 0.38	0.18/ 0.38	ns
		XC2VPX70	0.18/ 0.37	0.18/ 0.38	0.18/ 0.38	ns
		XC2VP100	N/A	0.18/ 0.33	0.19/ 0.37	ns

Notes:
1. The timing values were measured using the fine-phase adjustment feature of the DCM. These measurements include:
   - CLK0 and CLK180 DCM jitter
   - Worst-case duty-cycle distortion using CLK0 and CLK180, T_{DCD_CLK180}

   Package skew is not included in these measurements.
2. IFF = Input Flip-Flop

Source Synchronous Timing Budgets

This section describes how to use the parameters provided in the Source-Synchronous Switching Characteristics section to develop system-specific timing budgets. The following analysis provides information necessary for determining Virtex-II Pro contributions to an overall system timing analysis; no assumptions are made about the effects of Inter-Symbol Interference or PCB skew.

Virtex-II Pro Transmitter Data-Valid Window (T_X)

T_X is the minimum aggregate valid data period for a source-synchronous data bus at the pins of the device and is calculated as follows:

T_X = Data Period - [Jitter(1) + Duty Cycle Distortion(2) + TCKSKEW(3) + TPKGSKEW(4)]

Notes:
1. Jitter values and accumulation methodology to be provided in a future release of this document. The absolute period jitter values found in the DCM Timing Parameters section of the particular DCM output clock used to clock the IOB FF can be used for a best case analysis.
2. This value depends on the clocking methodology used. See Note1 for Table 64.
3. This value represents the worst-case clock-tree skew observable between sequential I/O elements. Significantly less clock-tree skew exists for I/O registers that are close to each other and fed by the same or adjacent clock-tree branches. Use the Xilinx FPGA_Editor and Timing Analyzer tools to evaluate clock skew specific to your application.
4. These values represent the worst-case skew between any two balls of the package: shortest flight time to longest flight time from Pad to Ball.

Table 5: **FG256/FGG256 — XC2VP2 and XC2VP4**

Bank	Pin Description	Pin Number
3	IO_L05P_3	L13
3	IO_L03N_3/VREF_3	L12
3	IO_L03P_3	M13
3	IO_L02N_3	M16
3	IO_L02P_3	N16
3	IO_L01N_3/VRP_3	M15
3	IO_L01P_3/VRN_3	M14
4	IO_L01N_4/BUSY/DOUT(1)	P15
4	IO_L01P_4/INIT_B	P14
4	IO_L02N_4/D0/DIN(1)	R14
4	IO_L02P_4/D1	P13
4	IO_L03N_4/D2	T15
4	IO_L03P_4/D3	T14
4	IO_L06N_4/VRP_4	N12
4	IO_L06P_4/VRN_4	P12
4	IO_L07P_4/VREF_4	N11
4	IO_L09N_4	M11
4	IO_L09P_4/VREF_4	M10
4	IO_L69N_4	N10
4	IO_L69P_4/VREF_4	P10
4	IO_L74N_4/GCLK3S	N9
4	IO_L74P_4/GCLK2P	P9
4	IO_L75N_4/GCLK1S	R9
4	IO_L75P_4/GCLK0P	T9
5	IO_L75N_5/GCLK7S	T8
5	IO_L75P_5/GCLK6P	R8
5	IO_L74N_5/GCLK5S	P8
5	IO_L74P_5/GCLK4P	N8
5	IO_L69N_5/VREF_5	P7
5	IO_L69P_5	N7
5	IO_L09N_5/VREF_5	M7
5	IO_L09P_5	M6
5	IO_L07N_5/VREF_5	N6

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
1	IO_L45N_1/VREF_1	C18			
1	IO_L45P_1	D18			
1	IO_L43N_1	E18			
1	IO_L43P_1	F18			
1	IO_L39N_1	G18			
1	IO_L39P_1	H18			
1	IO_L37N_1	A19			
1	IO_L37P_1	B19			
1	IO_L09N_1/VREF_1	E19			
1	IO_L09P_1	F19			
1	IO_L07N_1	G19			
1	IO_L07P_1	H19			
1	IO_L06N_1	C20			
1	IO_L06P_1	D20			
1	IO_L05_1/No_Pair	E20			
1	IO_L03N_1/VREF_1	F20			
1	IO_L03P_1	G20			
1	IO_L02N_1	D21			
1	IO_L02P_1	E21			
1	IO_L01N_1/VRP_1	D22			
1	IO_L01P_1/VRN_1	E22			
2	IO_L01N_2/VRP_2	C25			
2	IO_L01P_2/VRN_2	C26			
2	IO_L02N_2	D25			
2	IO_L02P_2	D26			
2	IO_L03N_2	E23			
2	IO_L03P_2	F22			
2	IO_L04N_2/VREF_2	E25			
2	IO_L04P_2	E26			
2	IO_L06N_2	F21			
2	IO_L06P_2	G21			
2	IO_L24N_2	F23	NC		
2	IO_L24P_2	F24	NC		
2	IO_L31N_2	F25			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	RSVD	C23			
N/A	VBATT	A24			
N/A	TMS	B24			
N/A	TCK	B26			
N/A	TDO	D24			
N/A	CCLK	AE24			
N/A	PWRDWN_B	AF24			
N/A	DONE	AD23			
N/A	AVCCAUXRX16	AE23			
N/A	VTRXPAD16	AE22			
N/A	RXNPAD16	AF23			
N/A	RXPPAD16	AF22			
N/A	GNDA16	AD21			
N/A	TXPPAD16	AF21			
N/A	TXNPAD16	AF20			
N/A	VTTXPAD16	AE20			
N/A	AVCCAUXTX16	AE21			
N/A	AVCCAUXRX18	AE18			
N/A	VTRXPAD18	AE17			
N/A	RXNPAD18	AF18			
N/A	RXPPAD18	AF17			
N/A	GNDA18	AD16			
N/A	TXPPAD18	AF16			
N/A	TXNPAD18	AF15			
N/A	VTTXPAD18	AE15			
N/A	AVCCAUXTX18	AE16			
N/A	AVCCAUXRX19	AE12			
N/A	VTRXPAD19	AE11			
N/A	RXNPAD19	AF12			
N/A	RXPPAD19	AF11			
N/A	GNDA19	AD11			
N/A	TXPPAD19	AF10			
N/A	TXNPAD19	AF9			
N/A	VTTXPAD19	AE9			
N/A	AVCCAUXTX19	AE10			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	AVCCAUXRX19	AE15			
N/A	VTRXPAD19	AE16			
N/A	RXNPAD19	AF15			
N/A	RXPPAD19	AF16			
N/A	GNDA19	AD16			
N/A	TXPPAD19	AF17			
N/A	TXNPAD19	AF18			
N/A	VTTXPAD19	AE18			
N/A	AVCCAUXTX19	AE17			
N/A	AVCCAUXRX21	AE20	NC	NC	
N/A	VTRXPAD21	AE21	NC	NC	
N/A	RXNPAD21	AF20	NC	NC	
N/A	RXPPAD21	AF21	NC	NC	
N/A	GNDA21	AD22	NC	NC	
N/A	TXPPAD21	AF22	NC	NC	
N/A	TXNPAD21	AF23	NC	NC	
N/A	VTTXPAD21	AE23	NC	NC	
N/A	AVCCAUXTX21	AE22	NC	NC	
N/A	VCCINT	H8			
N/A	VCCINT	J9			
N/A	VCCINT	K9			
N/A	VCCINT	U9			
N/A	VCCINT	V9			
N/A	VCCINT	W8			
N/A	VCCINT	H19			
N/A	VCCINT	J10			
N/A	VCCINT	J17			
N/A	VCCINT	J18			
N/A	VCCINT	K11			
N/A	VCCINT	K16			
N/A	VCCINT	K18			
N/A	VCCINT	L10			
N/A	VCCINT	L17			
N/A	VCCINT	T10			
N/A	VCCINT	T17			
N/A	VCCINT	U11			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	RXPPAD7		A12			
N/A	RXNPAD7		A11			
N/A	VTRXPAD7		B12			
N/A	AVCCAUXRX7		B11			
N/A	AVCCAUXTX9		B6			
N/A	VTTXPAD9		B7			
N/A	TXNPAD9		A7			
N/A	TXPPAD9		A6			
N/A	GNDA9		C6			
N/A	RXPPAD9		A5			
N/A	RXNPAD9		A4			
N/A	VTRXPAD9		B5			
N/A	AVCCAUXRX9		B4			
N/A	AVCCAUXRX16		AJ4			
N/A	VTRXPAD16		AJ5			
N/A	RXNPAD16		AK4			
N/A	RXPPAD16		AK5			
N/A	GNDA16		AH6			
N/A	TXPPAD16		AK6			
N/A	TXNPAD16		AK7			
N/A	VTTXPAD16		AJ7			
N/A	AVCCAUXTX16		AJ6			
N/A	AVCCAUXRX18		AJ11			
N/A	VTRXPAD18		AJ12			
N/A	RXNPAD18		AK11			
N/A	RXPPAD18		AK12			
N/A	GNDA18		AH12			
N/A	TXPPAD18		AK13			
N/A	TXNPAD18		AK14			
N/A	VTTXPAD18		AJ14			
N/A	AVCCAUXTX18		AJ13			
N/A	AVCCAUXRX19		AJ17			
N/A	VTRXPAD19		AJ18			
N/A	RXNPAD19		AK17			
N/A	RXPPAD19		AK18			
N/A	GNDA19		AH19			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		C14			
N/A	GND		C3			
N/A	GND		B29			
N/A	GND		B2			
N/A	GND		A22			
N/A	GND		A9			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L11N_2	L9		
2	IO_L11P_2	M10		
2	IO_L12N_2	H4		
2	IO_L12P_2	J5		
2	IO_L13N_2	J1		
2	IO_L13P_2	J2		
2	IO_L14N_2	M8		
2	IO_L14P_2	N9		
2	IO_L15N_2	K6		
2	IO_L15P_2	K7		
2	IO_L16N_2/VREF_2	K4		
2	IO_L16P_2	K5		
2	IO_L17N_2	P10		
2	IO_L17P_2	N10		
2	IO_L18N_2	K3		
2	IO_L18P_2	J3		
2	IO_L19N_2	K1		
2	IO_L19P_2	K2		
2	IO_L20N_2	M11		
2	IO_L20P_2	N11		
2	IO_L21N_2	L7		
2	IO_L21P_2	L8		
2	IO_L22N_2/VREF_2	L5		
2	IO_L22P_2	L6		
2	IO_L23N_2	P8		
2	IO_L23P_2	P9		
2	IO_L24N_2	L3		
2	IO_L24P_2	L4		
2	IO_L25N_2	L1		
2	IO_L25P_2	L2		
2	IO_L26N_2	P11		
2	IO_L26P_2	P12		
2	IO_L27N_2	M6		
2	IO_L27P_2	M7		
2	IO_L28N_2/VREF_2	M2		
2	IO_L28P_2	M3		
2	IO_L29N_2	R9		
2	IO_L29P_2	R10		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L49N_2	U5		
2	IO_L49P_2	U6		
2	IO_L50N_2	U13		
2	IO_L50P_2	V13		
2	IO_L51N_2	U4		
2	IO_L51P_2	T4		
2	IO_L52N_2/VREF_2	U1		
2	IO_L52P_2	U2		
2	IO_L53N_2	V9		
2	IO_L53P_2	V10		
2	IO_L54N_2	V7		
2	IO_L54P_2	V8		
2	IO_L55N_2	V5		
2	IO_L55P_2	V6		
2	IO_L56N_2	V11		
2	IO_L56P_2	V12		
2	IO_L57N_2	V3		
2	IO_L57P_2	V4		
2	IO_L58N_2/VREF_2	V1		
2	IO_L58P_2	V2		
2	IO_L59N_2	W10		
2	IO_L59P_2	W11		
2	IO_L60N_2	W7		
2	IO_L60P_2	W8		
2	IO_L85N_2	W5		
2	IO_L85P_2	W6		
2	IO_L86N_2	W12		
2	IO_L86P_2	W13		
2	IO_L87N_2	W3		
2	IO_L87P_2	W4		
2	IO_L88N_2/VREF_2	Y7		
2	IO_L88P_2	Y8		
2	IO_L89N_2	W9		
2	IO_L89P_2	Y9		
2	IO_L90N_2	Y3		
2	IO_L90P_2	Y4		
3	IO_L90N_3	AA7		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCINT		AF16		
N/A	VCCINT		AG27		
N/A	VCCINT		AG26		
N/A	VCCINT		AG25		
N/A	VCCINT		AG24		
N/A	VCCINT		AG23		
N/A	VCCINT		AG22		
N/A	VCCINT		AG21		
N/A	VCCINT		AG20		
N/A	VCCINT		AG19		
N/A	VCCINT		AG18		
N/A	VCCINT		AG17		
N/A	VCCINT		AG16		
N/A	VCCINT		AH28		
N/A	VCCINT		AH27		
N/A	VCCINT		AH26		
N/A	VCCINT		AH17		
N/A	VCCINT		AH16		
N/A	VCCINT		AH15		
N/A	VCCINT		AJ29		
N/A	VCCINT		AJ28		
N/A	VCCINT		AJ27		
N/A	VCCINT		AJ16		
N/A	VCCINT		AJ15		
N/A	VCCINT		AJ14		
N/A	VCCINT		AK30		
N/A	VCCINT		AK13		
N/A	VCCINT		AA27		
N/A	VCCINT		AA16		
N/A	VCCINT		Y27		
N/A	VCCINT		Y16		
N/A	VCCINT		W27		
N/A	VCCINT		W16		
N/A	VCCINT		V27		
N/A	VCCINT		V16		
N/A	VCCINT		U27		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCAUX		AM11		
N/A	VCCAUX		AN33		
N/A	VCCAUX		AN10		
N/A	VCCAUX		AV39		
N/A	VCCAUX		AV4		
N/A	VCCAUX		AW38		
N/A	VCCAUX		AW22		
N/A	VCCAUX		AW21		
N/A	VCCAUX		AW5		
N/A	VCCAUX		AA42		
N/A	VCCAUX		AA41		
N/A	VCCAUX		AA2		
N/A	VCCAUX		AA1		
N/A	VCCAUX		Y42		
N/A	VCCAUX		Y1		
N/A	VCCAUX		L32		
N/A	VCCAUX		L11		
N/A	VCCAUX		K33		
N/A	VCCAUX		K10		
N/A	VCCAUX		E39		
N/A	VCCAUX		E4		
N/A	VCCAUX		D38		
N/A	VCCAUX		D22		
N/A	VCCAUX		D21		
N/A	VCCAUX		D5		
N/A	GND		AB38		
N/A	GND		AB35		
N/A	GND		AB32		
N/A	GND		AB26		
N/A	GND		AB25		
N/A	GND		AB24		
N/A	GND		AB23		
N/A	GND		AB22		
N/A	GND		AB21		
N/A	GND		AB20		
N/A	GND		AB19		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
3	IO_L06N_3	BA8	
3	IO_L06P_3	BB8	
3	IO_L05N_3	AW8	
3	IO_L05P_3	AW9	
3	IO_L04N_3	BA7	
3	IO_L04P_3	BB7	
3	IO_L03N_3/VREF_3	BA6	
3	IO_L03P_3	BB6	
3	IO_L02N_3	AY9	
3	IO_L02P_3	BA9	
3	IO_L01N_3/VRP_3	BA4	
3	IO_L01P_3/VRN_3	BB4	
4	IO_L01N_4/BUSY/DOUT(1)	AL11	
4	IO_L01P_4/INIT_B	AL12	
4	IO_L02N_4/D0/DIN(1)	AV10	
4	IO_L02P_4/D1	AU10	
4	IO_L03N_4/D2	AN11	
4	IO_L03P_4/D3	AM11	
4	IO_L05_4/No_Pair	AT10	
4	IO_L06N_4/VRP_4	AY11	
4	IO_L06P_4/VRN_4	AY10	
4	IO_L07N_4	BB10	
4	IO_L07P_4/VREF_4	BA10	
4	IO_L08N_4	AU11	
4	IO_L08P_4	AT11	
4	IO_L09N_4	AR11	
4	IO_L09P_4/VREF_4	AP11	
4	IO_L19N_4	AW11	
4	IO_L19P_4	AV11	
4	IO_L20N_4	BB11	
4	IO_L20P_4	BA11	
4	IO_L21N_4	AN12	
4	IO_L21P_4	AM12	
4	IO_L25N_4	AR13	
4	IO_L25P_4	AT12	
4	IO_L26N_4	AV12	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
4	IO_L26P_4	AU12	
4	IO_L27N_4	AR12	
4	IO_L27P_4/VREF_4	AP12	
4	IO_L28N_4	AW13	
4	IO_L28P_4	AW12	
4	IO_L29N_4	BA12	
4	IO_L29P_4	AY12	
4	IO_L30N_4	AN13	
4	IO_L30P_4	AM13	
4	IO_L34N_4	AU13	
4	IO_L34P_4	AT13	
4	IO_L35N_4	BA13	
4	IO_L35P_4	AY13	
4	IO_L36N_4	AM14	
4	IO_L36P_4/VREF_4	AL14	
4	IO_L76N_4	AR15	
4	IO_L76P_4	AT14	
4	IO_L77N_4	AV14	
4	IO_L77P_4	AU14	
4	IO_L78N_4	AP14	
4	IO_L78P_4	AN14	
4	IO_L79N_4	AW15	
4	IO_L79P_4	AY14	
4	IO_L80_4/No_Pair	BB14	
4	IO_L83_4/No_Pair	BA14	
4	IO_L84N_4	AM15	
4	IO_L84P_4	AL15	
4	IO_L85N_4	AT16	
4	IO_L85P_4	AT15	
4	IO_L86N_4	AV15	
4	IO_L86P_4	AU15	
4	IO_L87N_4	AP15	
4	IO_L87P_4/VREF_4	AN15	
4	IO_L37N_4	AY16	
4	IO_L37P_4	AY15	
4	IO_L38N_4	BB15	
4	IO_L38P_4	BA15	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L33N_6/VREF_6	AK40	
6	IO_L34P_6	AK36	
6	IO_L34N_6	AK37	
6	IO_L35P_6	AE36	
6	IO_L35N_6	AE37	
6	IO_L36P_6	AJ41	
6	IO_L36N_6	AJ42	
6	IO_L37P_6	AJ40	
6	IO_L37N_6	AH40	
6	IO_L38P_6	AE34	
6	IO_L38N_6	AE35	
6	IO_L39P_6	AJ38	
6	IO_L39N_6/VREF_6	AH37	
6	IO_L40P_6	AJ36	
6	IO_L40N_6	AJ37	
6	IO_L41P_6	AE32	
6	IO_L41N_6	AE33	
6	IO_L42P_6	AH41	
6	IO_L42N_6	AH42	
6	IO_L43P_6	AH38	
6	IO_L43N_6	AH39	
6	IO_L44P_6	AD36	
6	IO_L44N_6	AC35	
6	IO_L45P_6	AH36	
6	IO_L45N_6/VREF_6	AG36	
6	IO_L46P_6	AG41	
6	IO_L46N_6	AG42	
6	IO_L47P_6	AD34	
6	IO_L47N_6	AC33	
6	IO_L48P_6	AG40	
6	IO_L48N_6	AF39	
6	IO_L49P_6	AG38	
6	IO_L49N_6	AG39	
6	IO_L50P_6	AD32	
6	IO_L50N_6	AD33	
6	IO_L51P_6	AG37	
6	IO_L51N_6/VREF_6	AF37	

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	VCCO_5	AL30	
5	VCCO_5	AW29	
5	VCCO_5	AR29	
5	VCCO_5	AJ26	
5	VCCO_5	AW25	
5	VCCO_5	AR25	
5	VCCO_5	AJ25	
5	VCCO_5	AH25	
5	VCCO_5	AJ24	
5	VCCO_5	AH24	
5	VCCO_5	AJ23	
5	VCCO_5	AH23	
5	VCCO_5	AJ22	
5	VCCO_5	AH22	
4	VCCO_4	AJ21	
4	VCCO_4	AH21	
4	VCCO_4	AJ20	
4	VCCO_4	AH20	
4	VCCO_4	AJ19	
4	VCCO_4	AH19	
4	VCCO_4	AW18	
4	VCCO_4	AR18	
4	VCCO_4	AJ18	
4	VCCO_4	AH18	
4	VCCO_4	AJ17	
4	VCCO_4	AW14	
4	VCCO_4	AR14	
4	VCCO_4	AL13	
4	VCCO_4	AW10	
3	VCCO_3	AG15	
3	VCCO_3	AF15	
3	VCCO_3	AE15	
3	VCCO_3	AD15	
3	VCCO_3	AC15	
3	VCCO_3	AB15	
3	VCCO_3	AH14	
3	VCCO_3	AG14	